

Others

- 1) J. H. Tung, C. S. Chen, W. Y. Zhao and C. M. Tan, “Optimization of sandblasting process of complex 3D surface polishing using variable viscoelastic diamond particles abrasive”, 3rd International Conference on Automation, Mechanical Control and Computational Engineering (AMCCE), Dalian, China, May 2018.
- 2) J. Zhang, X. Y. Zhang, Z. L. Chen, K. Y. See, C. M. Tan, and S. S. Chen. “On-chip RF energy harvesting circuit for image sensor,” in Int. Symp. on Integrated Circuits, 2011, pp. 420-423.
- 3) J. W. Zhang, L. B. Wang, K. Y. See, C. M. Tan, C. C. Boon, K. S. Yeo, and M. A. Do. “Wireless energy harvesting using serially connected voltage doublers,” in Asia-Pacific Microwave Conf., Yokohama, Japan, 2010.
- 4) C. M. Tan, K. Y. See, J. W. Zhang, M. J. Xu, C. C. Boon, K. S. Yeo, and M. A. Do. “A possible reality on battery-less low-power portable electronics,” in IEEE Conf. on Industrial Electronics and Applications, Taichung, Taiwan, 2010, pp. 630-633.
- 5) Z.J. Han, M. Shakerzadeh, B.K. Tay, C.M. Tan, “Protein immobilization on nanostructured surfaces with different wettability,” in 2010 IEEE 3rd International Nanoelectronics Conference (INEC 2010), p 1 pp., 2010
- 6) Y. Hou and C.M. Tan. “Transient electrical thermal

analysis of ESD process using 3-D finite element method,” in 12th IEEE Int. Symp. on Integrated Circuits, Singapore, 2009.

7) C. M. Tan, E. Q. Kuan, and R. Cai. “The influence of Nano TiO₂ film thickness on its photo-catalytic and hydrophilic properties,” presented at Advanced Materials for Nanotechnology, New Zealand, May 2009.

8) C. M. Tan. “Extending the useful life of solar cell through Nano TiO₂ film coating,” presented at Advanced Materials for Nanotechnology, New Zealand, May 2009.

9) C. M. Tan, L. Sun, and C. Wang. “Going green for discrete power diode manufacturing,” presented at IEEE ICIEA2009, Xi'an, China.

10) I. V. McLoughlin, A. M. Prakash, S. Shukla, S. H. Tan, K. Arichandran, C. M. Tan, V. S. Sawant, and R. K. Manchanda. “Use of high altitude balloon platforms for small satellite testing,” in IEEE Int. Workshop on Digital infoTainment and Visualization, 2008, pp. 1-5.

11) C. M. Tan, L. Sun, N. Raghavan, G. Huang, C. Hsu, and C. Wang. “The physical limit and manufacturability of power diode with carrier lifetime control,” in Int. Conf. on industrial electronics and applications, 2007.

12) N. Raghavan, N. Hwang, and C. M. Tan. “A comprehensive semi-empirical mobility model for strained-Si N-MOSFETs,” in 8th Int. Conf. on Solid-State

and Integrated Circuit Technology, 2006, pp. 139-142.

13) C. M. Tan and Z. Gan. “Building empirical model through simulation a case study,” in Int. Conf. on Engineering Management, 2004, pp. 1090-1094.

14) C. M. Tan, Y. H. Sng, and H. K. Tang “Industry-university R&D collaboration: expectation and reality,” in Int. Conf. on Engineering Management, 2004, pp. 626-629.

15) Z. L. Yuan, D. H. Zhang, C. Y. Li, K. Prasad, L. J. Tang, C. M. Tan, R. Kumar, and P.D. Foo. “Study of interaction between a-Ta films and SiO₂ under rapid thermal annealing,” in Int. Conf. on Materials for Advanced Technologies, 2003.

16) K. Prasad, X. L. Yuan, C. M. Tan, D. H. Zhang, C. Y. Li, S. R. Wang, S. Y. J. Yuan, J. L. Xie, D. Gui, and P. D. Foo. “Diffusion studies of Cu in Si and low-k dielectric materials,” in Materials Research Society Spring Meeting, 2002.

17) S. Zukotynski, F. Gaspari, N. Kherani, T. Kostas, K. Law, W. T. Shmayda, and C. M. Tan. “Metastability in tritiated amorphous silicon,” in 19th Int. Conf. on Amorphous and Microcrystalline Semiconductors Science & Technology, 2001.

18) K. Prasad, D. H. Zhang, C. M. Tan. “Backside copper contamination issues in CMOS integrated circuits,” in Int. workshop on physics of semiconductor devices, 2001.

19) P. Ranjan, H. Pandey, M. R. Tripathy, C. M. Tan, and

S. Pushp "Reliability Ranking of Nodes: A Case of Revolution." Progress in Electromagnetics Research Symposium (PIERS), Toyama, Japan, pp. 1542-1549. Aug,2018.

